



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 09/464,322

Filing Date: December 15, 1999

Applicant: Heung-Kyu KWON et al.

Group Art Unit: 2815

Examiner: Chris C. CHU

Title: SEMICONDUCTOR CHIP PACKAGE AND METHOD OF  
FABRICATING THE SAME

Attorney Docket: 25611-000085/US

Customer Service Window  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314  
Mail Stop AF Amendment

September 14, 2006

AMENDMENT AFTER FINAL REJECTION UNDER 35 C.F.R. § 1.116

Sir:

In response to the Office Action mailed June 21, 2006, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Specification begin on page 2 of this Amendment.

Amendments to the Claims begin on page 3 of this Amendment.

Remarks begin on page 7 of this Amendment.

	Claims remaining after Amendment		Highest number previously paid for		Present extra
Total	18	-	20	=	0
Independent	3	-	3	=	0